

Technical Data Sheet

FeedBond® EP-3600-WL2

Insulated Thermally Conductive Adhesive

Description:

FeedBond®EP-3600-WL2 is a modified epoxy type thermal conductive adhesive, apply for thermal management of electronic devices . It serves as an effective thermal interface material for heat sink devices where efficient cooling as well as long-term stability is required..

Application Package:

Devices which need high thermal conductivity(Power Devices,RF ICs and LEDs)

Characteristics:

- High thermal conductivity
- Low drying during process
- Low bleed.

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	White		
Viscosity @ 25°C	35000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	2.5	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	<25µm	Grind meter	FT-P026
Work Life @ 25°C	48hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6months	25% increase in visc. @ 5rpm	FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		90 minutes in oven @110°C	

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

FeedBond® EP-3600-WL2

PHYSIOCHEMICAL PROPERTIES	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature (Tg) 139°C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		
Below Tg(α 1) 37 ppm/°C	TMA Expansion Mode	FT-M016
Above Tg(α 2) 89 ppm/°C		
Dynamic Tensile Modulus		
@25°C 6930MPa	Dynamic Mechanical Thermal Analysis using <1.6 mm thick specimen	FT-M019A
@150°C 2328MPa		
@250°C 768MPa		
Thermal conductivity 2.0W/mK	Hot Disk	FT-P022
MECHANICAL PROPERTIES-POST CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C >3Kg/die	45mil × 45mil die on Ag Leadframe	FT-M012

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

Thawing

Place the container to stand vertically for 60mins.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Storage Temp.	-42°C~-35°C	-22°C~-18°C	0°C~5°C	18°C~28°C
Shelf Life	6 months	6 months	3 months	2 days

Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.